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FOR IMMEDIATE RELEASE

Press Release

YINCAE President, Dr. Wusheng Yin, presents:

“The Future of Solder Joint Encapsulation”

IPC Tech Summit 2014 in Raleigh, NC

(Albany, NY) October 24, 2014. Dr. Wusheng Yin, President of YINCAE Advanced Materials LLC, will be presenting in the Technical Session on *“The Future of Solder Joint Encapsulation”* at the upcoming IPC Tech Summit, with the event being held from Oct 28th to 30th in Raleigh, NC.

Following is the Abstract taken from the paper on *“The Future of Solder Joint Encapsulation”*

“Solder joint encapsulant adhesives have been successfully used for many years by major electronics manufacturers to enhance the strength of solder joints. These products have proven to strengthen solder joints 5-10x over traditional methods, and have greatly improved thermal cycling during the soldering process as well as the drop performance in the finished products. The use of solder joint encapsulant adhesives can eliminate the need for underfill materials and the underfill process altogether, thus simplifying rework, which results in a lower cost of ownership. Solder joint strength, however, continues to be a problematic issue with increased package on package and system on package miniaturization.

Research tests were performed to compare the solder joint strength using flux in nitrogen reflow process versus solder joint encapsulant in air reflow process. Using flux in nitrogen, the top PoP had a solder joint height of 11.85 mil with 0.9 mil warpage and 5.25% solder voids. In comparison, using solder joint encapsulant in air, the PoP had a solder joint height of 11.33 mil with 0.8 mil warpage and 2.93%

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solder voids. The pull strength of solder joint was 71N using flux compared to 352N using the solder joint encapsulant. The first thermal cycling failure was increased from 495 cycles using underfill, to around 5000 cycles using the solder joint encapsulant. From the data, it is evident that solder joint encapsulant provides a very promising solution for solder joint strength in the evolution of miniaturized electronic packaging. In this presentation, we are going to discuss the details and future of solder joint encapsulant adhesives.”

The IPC Organization holds several key technical events throughout the calendar year and YINCAE Advanced Materials is pleased to be a corporate member and event participant. YINCAE Advanced Materials will exhibit at the IPC APEX Expo held February 2015 in San Diego, CA.

Visit the web link at www.yincae.com for information on the range of Advanced Materials or Email Taylor Farrell: tfarrell@yincae.com Phone number: (518) 452-2880 HQ in Albany, NY

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YINCAE Advanced Materials, LLC is a leading manufacturer and supplier of high-performance coatings, adhesives and encapsulants used in the computer microchip and optoelectronics industries. Our manufacturing operations and headquarters are located in Albany, NY USA, with technical sales and support available through a worldwide sales and service organization.

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